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BC807-16LT1, BC807-25LT1, BC807-40LT1

General Purpose Transistors

PNP Silicon

Features

• Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V_{CEO}	-45	V
Collector – Base Voltage	V _{CBO}	-50	V
Emitter – Base Voltage	V _{EBO}	-5.0	V
Collector Current – Continuous	Ic	-500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

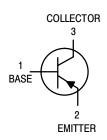
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in 99.5% alumina.



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SOT-23 CASE 318 STYLE 6

MARKING DIAGRAM



5xx = Device Codexx = A1, B1, or C

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

BC807-16LT1, BC807-25LT1, BC807-40LT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	-				
Collector – Emitter Breakdown Voltage (I _C = –10 mA)	V _{(BR)CEO}	-45	_	-	V
Collector – Emitter Breakdown Voltage ($V_{EB} = 0$, $I_{C} = -10 \mu A$)	V _{(BR)CES}	-50	_	-	V
Emitter – Base Breakdown Voltage (I _E = –1.0 μA)	V _{(BR)EBO}	-5.0	_	-	V
Collector Cutoff Current $(V_{CB} = -20 \text{ V})$ $(V_{CB} = -20 \text{ V}, T_J = 150^{\circ}\text{C})$	I _{CBO}	- -	_ _	-100 -5.0	nA μA
ON CHARACTERISTICS					
DC Current Gain $ (I_{C} = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}) $ BC80' BC80' BC80' BC80'	7–25	100 160 250 40	- - -	250 400 600	-
Collector – Emitter Saturation Voltage (I _C = -500 mA, I _B = -50 mA)	V _{CE(sat)}	-	_	-0.7	V
Base – Emitter On Voltage (I _C = –500 mA, I _B = –1.0 V)	V _{BE(on)}	-	_	-1.2	V
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain - Bandwidth Product (I _C = -10 mA, V _{CE} = -5.0 Vdc, f = 100 MHz)	f _T	100	_	-	MHz
Output Capacitance $(V_{CB} = -10 \text{ V}, f = 1.0 \text{ MHz})$	C _{obo}	-	10	-0.7	pF

ORDERING INFORMATION

Device	Specific Marking	Package	Shipping [†]
BC807-16LT1		SOT-23	3000/Tape & Reel
BC807-16LT1G		SOT-23 (Pb-Free)	3000/Tape & Reel
BC807-16LT3	5A1	SOT-23	10,000/Tape & Reel
BC807-16LT3G		SOT-23 (Pb-Free)	10,000/Tape & Reel
BC807-25LT1		SOT-23	3000/Tape & Reel
BC807-25LT1G		SOT-23 (Pb-Free)	3000/Tape & Reel
BC807-25LT3	5B1	SOT-23	10,000/Tape & Reel
BC807-25LT3G		SOT-23 (Pb-Free)	10,000/Tape & Reel
BC807-40LT1		SOT-23	3000/Tape & Reel
BC807-40LT1G		SOT-23 (Pb-Free)	3000/Tape & Reel
BC807-40LT3	5C	SOT-23	10,000/Tape & Reel
BC807-40LT3G	07-40LT3G		10,000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

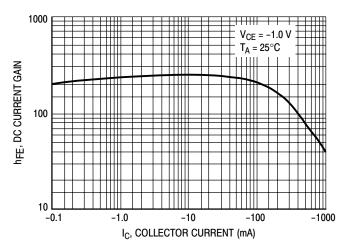


Figure 1. DC Current Gain

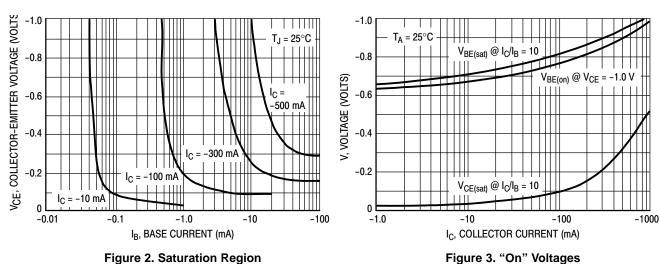


Figure 2. Saturation Region

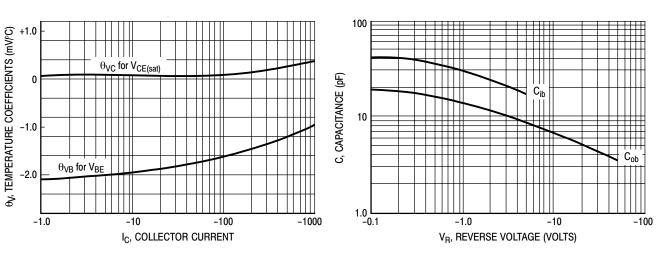


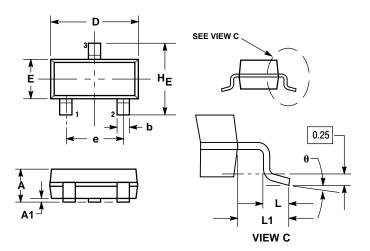
Figure 4. Temperature Coefficients

Figure 5. Capacitances

BC807-16LT1, BC807-25LT1, BC807-40LT1

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



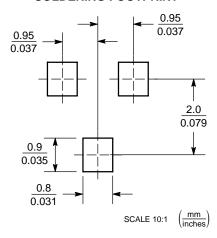
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- BASE MATERIAL. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

- PIN 1. BASE
 - 2. **EMITTER**
 - COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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